L Number	Hits	Search Text	DB	Time stamp
1	112	(((dielectric insulat\$3) and (hydrogen H2	USPAT;	2004/09/29 18:19
		"H.sub.2")) and (wet near10 (treat\$3	US-PGPUB	
		solution))) and ((dielectric insulat\$3)		
		near100 (hydrogen H2 "H.sub.2") near100 (wet		
		near10 (treat\$3 solution)))		
2	40	((((dielectric insulat\$3) and (hydrogen H2	USPAT;	2004/09/29 18:19
		"H.sub.2")) and (wet near10 (treat\$3	US-PGPUB	
		solution))) and ((dielectric insulat\$3)		
		near100 (hydrogen H2 "H.sub.2") near100 (wet		
		near10 (treat\$3 solution)))) and (argon Ar)		
3	10	(((dielectric insulat\$3) and (hydrogen H2	EPO; JPO;	2004/09/29 18:19
		"H.sub.2")) and (wet near10 (treat\$3	DERWENT;	
		solution))) and ((dielectric insulat\$3)	IBM TDB	l
		near100 (hydrogen H2 "H.sub.2") near100 (wet	_	
		near10 (treat\$3 solution)))		
5	0	(((dielectric insulat\$3) and (hydrogen H2	EPO; JPO;	2004/09/29 18:19
		"H.sub.2")) and (wet near10 (treat\$3	DERWENT;	
		solution))) and ((dielectric insulat\$3)	IBM TDB	
		near100 (hydrogen H2 "H.sub.2") near100 (wet		
		near10 (treat\$3 solution)))) and (argon Ar)		
6	10279	(ILD (inter near5 dielectric) IMD)	USPAT;	2004/09/29 18:39
-		((US-PGPUB	
7	3316	((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:39
		(hydrogen "H.sub.2")	US-PGPUB	2001,03,23 10:33
8	2351	(((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:39
		(hydrogen "H.sub.2")) and (wet solution)	US-PGPUB	2001/03/23 10:33
9	1440	((((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:21
_		(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	2004/03/23 10:21
		and (clean\$3 treat\$3)	OB TOTOB	
10	942		USPAT;	2004/09/29 18:21
	712	(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	2004/03/23 18:21
		and (clean\$3 treat\$3)) and plasma	OD FGFGB	
11	523	((((((ILD (inter near5 dielectric) IMD)) and	USPAT;	2004/09/29 18:22
	323	(hydrogen "H.sub.2")) and (wet solution))	US-PGPUB	2004/03/23 18.22
		and (clean\$3 treat\$3)) and plasma) and	OB FGFGB	1
		(argon "Ar")		
12	332	(((((((ILD (inter near5 dielectric) IMD))	USPAT;	2004/09/29 18:22
	332	and (hydrogen "H.sub.2")) and (wet	US-PGPUB	2004/03/23 18.22
		solution)) and (clean\$3 treat\$3)) and	US-FGFUB	1
		plasma) and (argon "Ar")) and (resist PR		
		photoresist)	ĺ	
13	327		USPAT;	2004/00/20 10.22
13	327	and (hydrogen "H.sub.2")) and (wet	US-PGPUB	2004/09/29 18:23
		solution)) and (clean\$3 treat\$3)) and	US-PGPUB	
		plasma) and (argon "Ar")) and (resist PR		
		photoresist)) and (etch\$3 pattern\$3)		
14	2414	(ILD (inter near5 dielectric) IMD)	EPO; JPO;	2004/09/29 18:39
±*	2717	(The (Three hears dielectric) The)		2004/09/29 18:39
			DERWENT;	
15	86	((IID (inter nearE dielogtrie) IMD() and	IBM_TDB	2004/00/20 10 20
10		((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")	EPO; JPO;	2004/09/29 18:39
		(mydrogen "m.sub.z")	DERWENT;	
16	14	((/TID /inter nears dialectric) TMD()	IBM_TDB	2004/00/00 10 10
7.0	14	(((ILD (inter near5 dielectric) IMD)) and	EPO; JPO;	2004/09/29 18:40
		(hydrogen "H.sub.2")) and (wet solution)	DERWENT;	
			IBM_TDB	